

HIGH-STRENGTH SOLDER JOINT

BACKGROUND OF THE INVENTION

This application is a division of co-pending Application No. 09/653,865, filed on September 1, 2000, ^(now U.S. Patent 6669077,) the entire contents of which are hereby incorporated by reference.

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5 1. Field of the invention

The present invention generally relates to soldering techniques, and in particular to a soldering method for a nickel/gold electroless plated surface. The present invention can be applied to a wiring structure, a circuit, and a method for
10 manufacturing the same.

2. Description of the Related Art

Soldering is used to not only electrically connect an electronic device to a printed circuit substrate but also mechanically fix it to the printed circuit substrate. Therefore,
15 to ensure a sufficient strength at a solder joint is one of the important issues in the field of mounting techniques.

In the case of an electronic device of relatively large in size, the electrode area thereof to be soldered, that is, solder-contact area, is also relatively large and therefore the
20 strength of a solder joint is not a significant issue in design. Since a mechanically sufficient solder joint strength is achieved